

## Topic 9

### JTAG Boundary-Scan

Peter Cheung  
Department of Electrical & Electronic Engineering  
Imperial College London

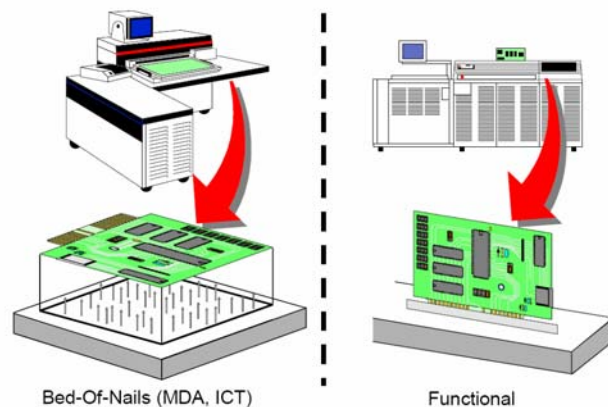
(Based on Ben Bennetts' Tutorial)

URL: [www.ee.imperial.ac.uk/pcheung/](http://www.ee.imperial.ac.uk/pcheung/)  
E-mail: [p.cheung@imperial.ac.uk](mailto:p.cheung@imperial.ac.uk)

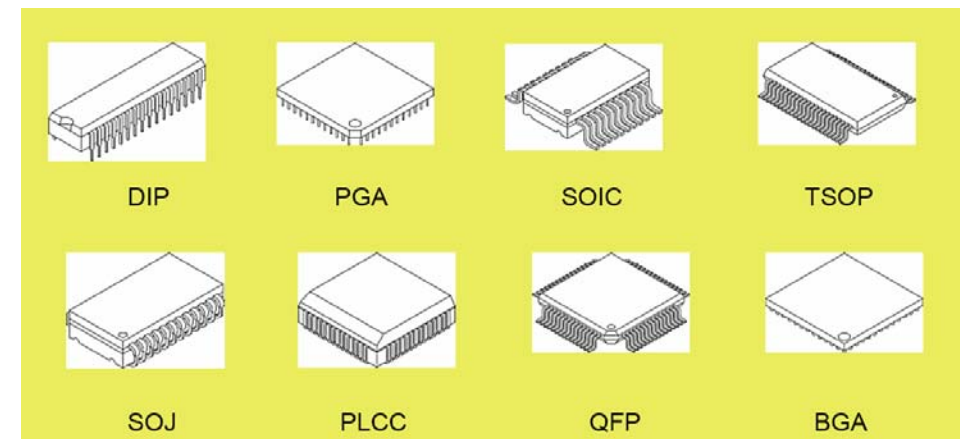
- ◆ JTAG Boundary Scan is from IEEE Standard 1149.1
- ◆ Most of slides here are based on the document "Boundary Scan Tutorial" by Ben Bennetts, for ASSET InterTech Inc., [www.asset-intertech.com/pdfs/boundaryscan\\_tutorial.pdf](http://www.asset-intertech.com/pdfs/boundaryscan_tutorial.pdf)

## The old way

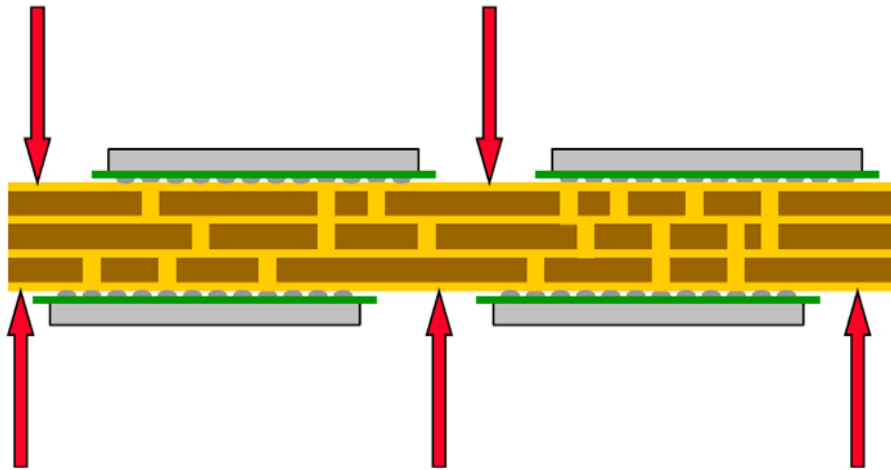
### In-Circuit & Functional Board Test



## Problem with modern packaging styles



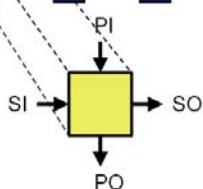
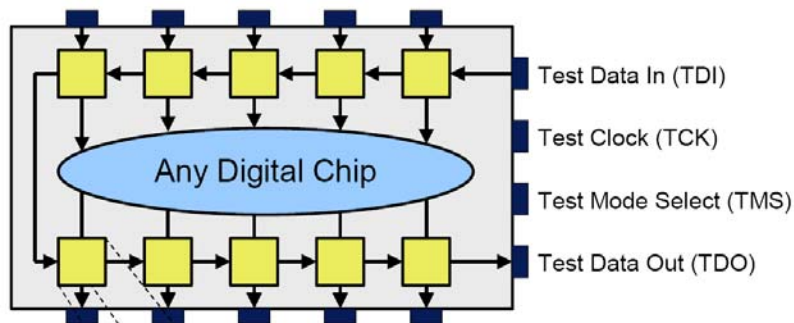
## Problem with multi-layer PCB



## Motivation of Boundary Scan

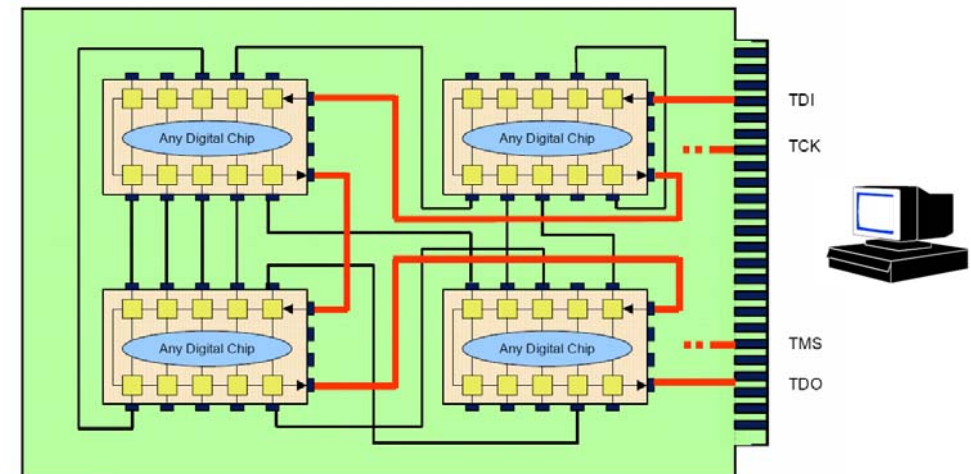
- Basic motivation was miniaturization of device packaging, leading to ...
  - surface mount packaging styles, leading to ...
  - double sided boards, leading to ...
  - multi-layer boards, leading to ...
  - a reduction of physical access test lands for traditional bed-of-nail in-circuit testers
- ↓
- Problem: how to test for manufacturing defects in the future?
  - Solution: add boundary-scan registers to the devices

## Principle of Boundary Scan

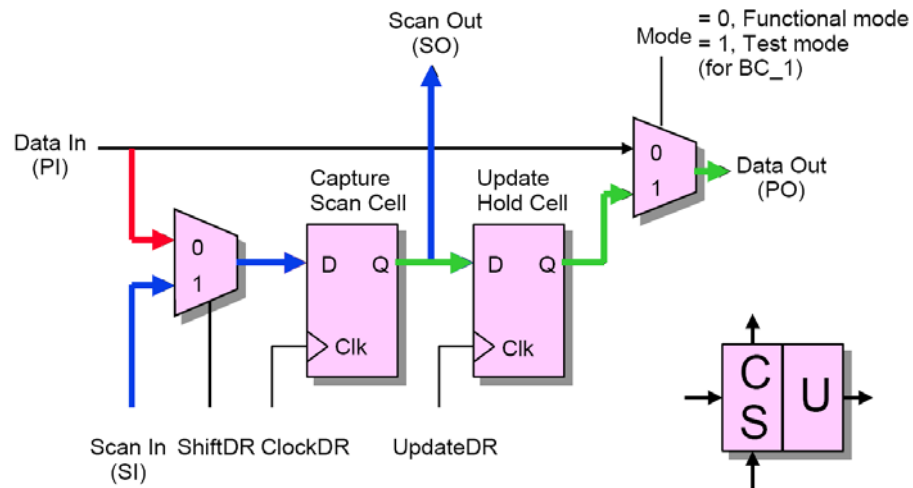


- Each boundary-scan cell can:
- Capture data on its parallel input PI
  - Update data onto its parallel output PO
  - Serially scan data from SO to its neighbour's SI
  - Behave transparently: PI passes to PO
  - Note: all digital logic is contained inside the boundary-scan register

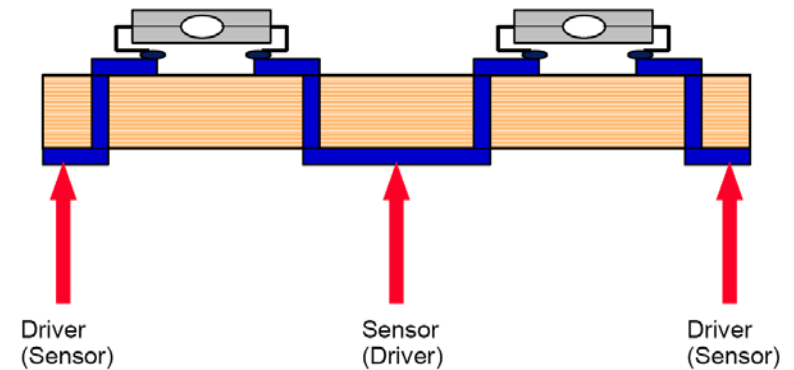
## The Boundary Scan Path



## Basic Boundary Scan Cell

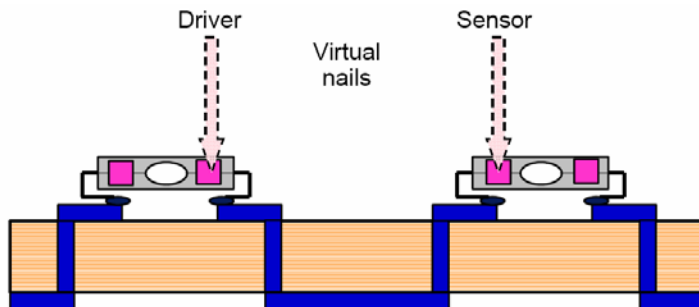


## Defect Coverage: Bed-of-nails



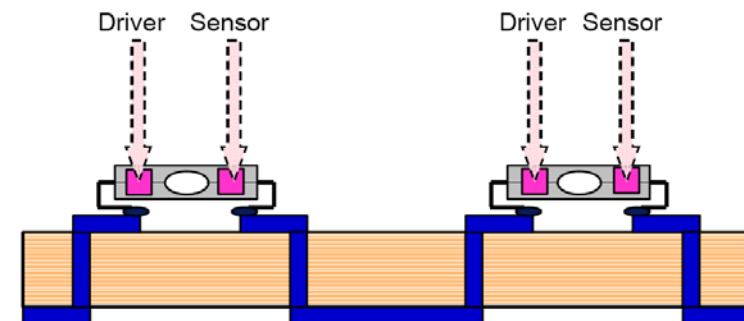
Defects covered: nail - plated-through-hole - interconnect  
- solder - leg - bond wire - device - bond wire - leg - solder  
- interconnect - plated through hole - nail

## Defect Coverage: Extest



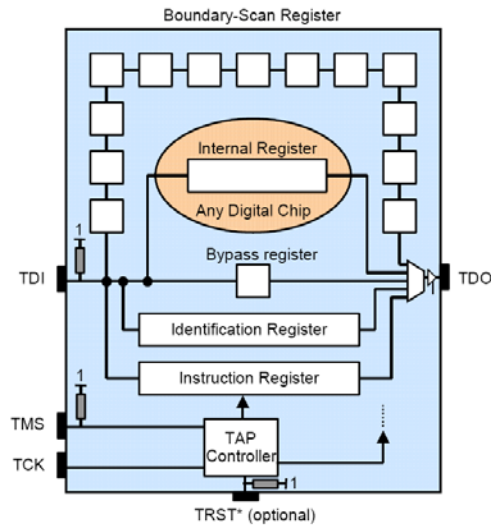
In this mode (EXternal TEST), defects covered:  
driver (TX) scan cell - driver amp - bond wire - leg - solder -  
interconnect  
- solder - leg - bond wire - driver amp - sensor (RX) scan cell

## Defect Coverage: Intest

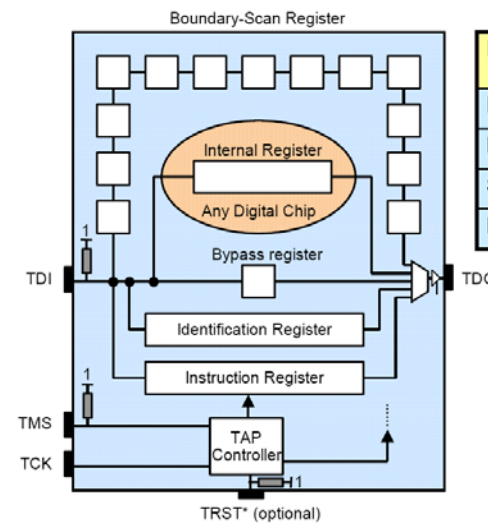


In this mode (INTERNAL TEST), defects covered:  
driver scan cell - device - sensor scan cell

## 1149.1 Chip Architecture



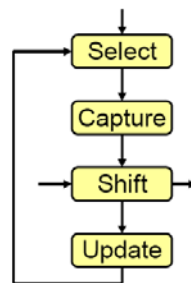
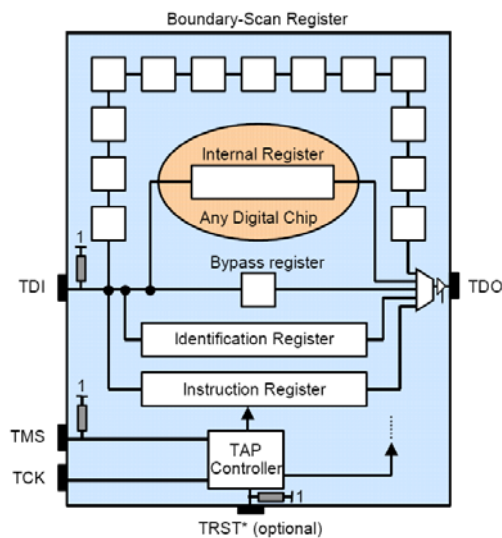
## Mandatory Instructions and Reset Modes



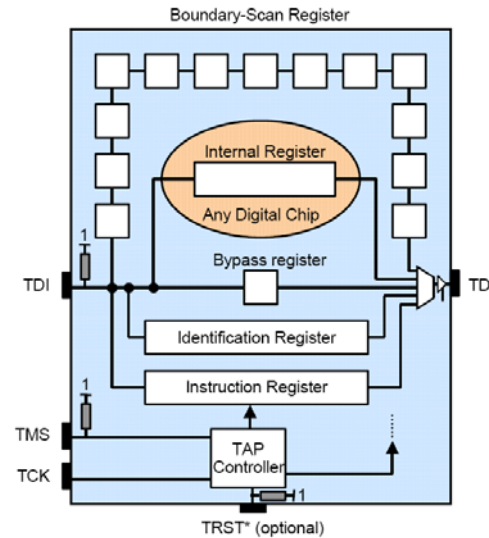
Instruction	Target (Active) Register	Code
Extest	Boundary Scan	Formerly All-0s
Bypass	Bypass	All-1s
Sample	Boundary Scan	Undefined
Preload	Boundary Scan	Undefined

$IR \geq 2$   
Reset:  
 $TMS = 1, 5 \times TCK$

## Target Register Modes

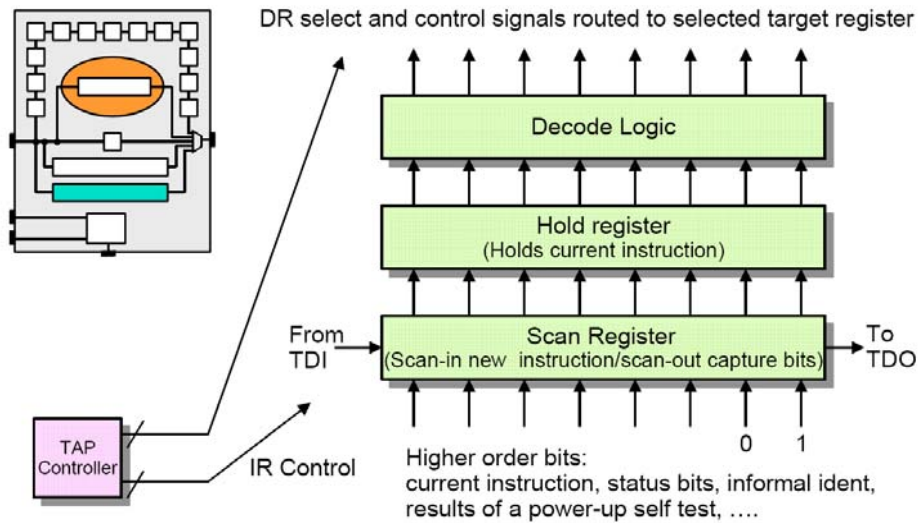


## Open-Circuit TDI, TMS and TRST\*?



- ❑ An open-circuit TDI, TMS or TRST\* must go to logic-1. Why?
- ❑ TDI: Bypass instruction is loaded: safe instruction
- ❑ TMS: TAP controller placed into Test\_Logic\_Reset state after 5 TCKs, max: safe state
- ❑ TRST\* not asserted. Rest of 1149.1 logic still usable

## Instruction Register

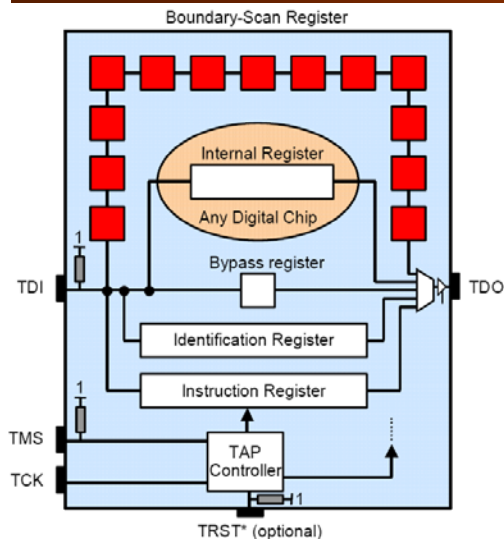


## Standard Instructions

Instruction	Selected Data Register
Mandatory: <b><u>Extest</u></b> <b><u>Bypass</u></b> <b><u>Sample</u></b> <b><u>Preload</u></b>	Boundary scan (formerly all-0s code) Bypass (initialised state, all-1s code) Boundary scan (device in functional mode) Boundary scan (device in functional mode)
Optional: <b><u>Intest</u></b> <b><u>Idcode</u></b> <b><u>Usercode</u></b> <b><u>Runbist</u></b> <b><u>Clamp</u></b> <b><u>HighZ</u></b>	Boundary scan Identification (initialised state if present) Identification (for PLDs) Result register Bypass (output pins in safe state) Bypass (output pins in high-Z state)

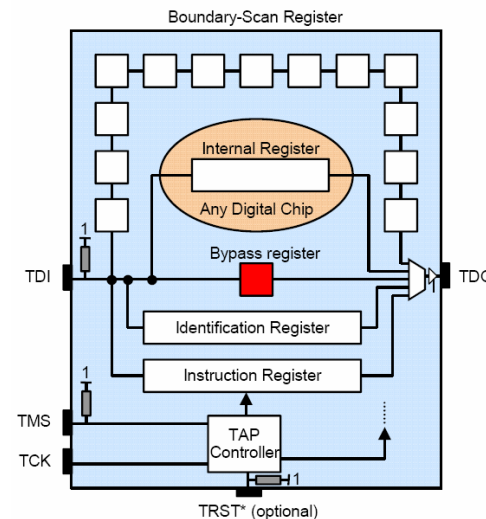
NB. All unused instruction codes must default to **Bypass**

## Extest Instructions



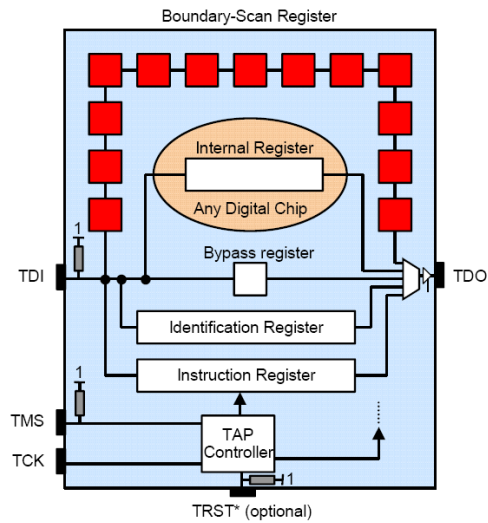
- Boundary-scan register selected
- Used to apply patterns to the interconnect structures on the board
- Boundary-scan cells have permission to write to their outputs (device in test mode)

## Bypass Instruction



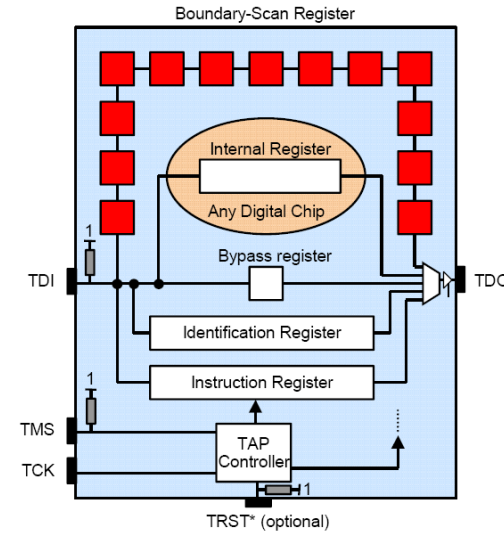
- Bypass register selected
- Used to allow quick passage through this device to another device connected in the chain

## Sample and Preload Instruction



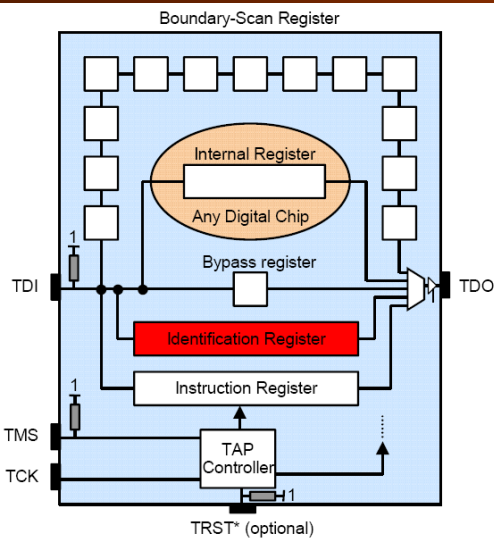
- Boundary scan register selected
- Used to Preload known values in the boundary scan cells.
- Also used to Sample (Capture) mission-mode signals into the boundary-scan cells
- Device in functional mode, not test mode

## Intest Instruction



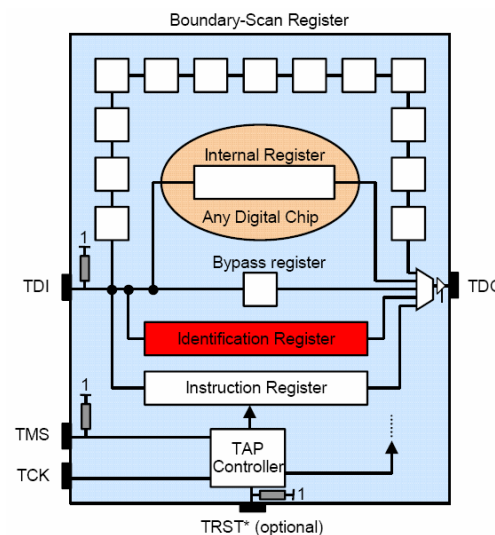
- Boundary scan register selected
- Used to apply patterns to the device itself
- Boundary scan cells have permission to write to their outputs (device in test mode)

## Idcode Instruction



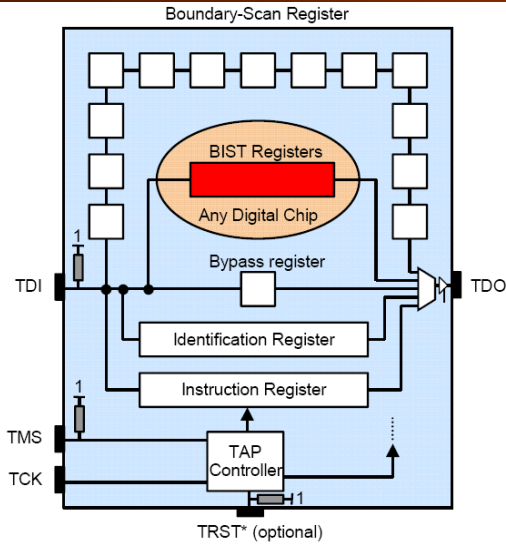
- Optional Identification register selected, if available, else Bypass register selected
- Used to capture internal 32-bit identification code (manufacturer, part number, version number) and then shift out through TDO

## Usercode Instruction



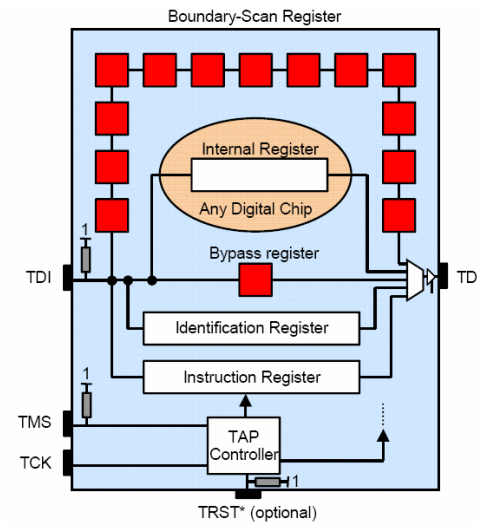
- Optional Identification register selected, if available, else Bypass register selected
- Use to capture an alternative 32-bit identification code for dual personality devices e.g. PLDs

## RunBIST Instruction



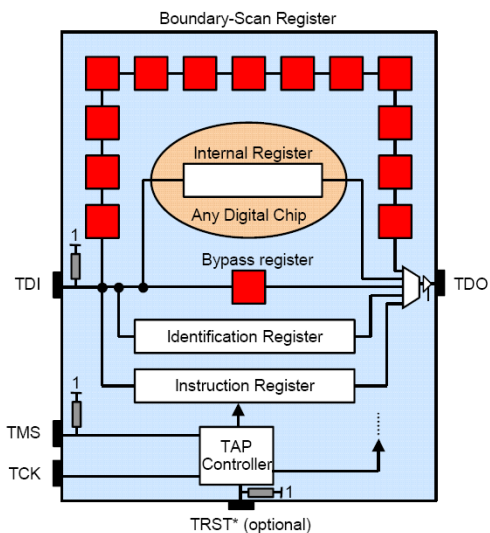
- ❑ Control registers for initiating internal BIST (Memory or Logic)
- ❑ Pass/fail register targeted as final selected register

## Clamp Instruction



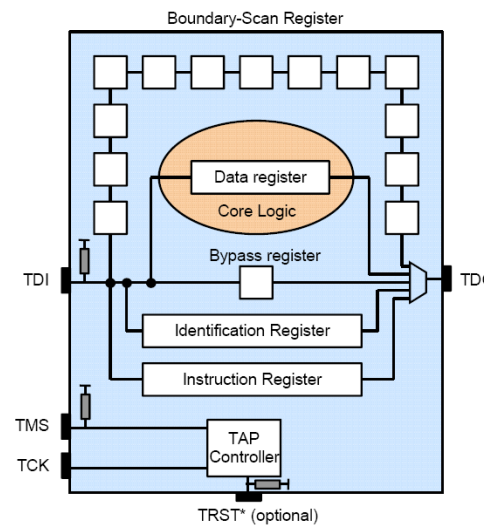
- ❑ Known values are pre-loaded into boundary scan cells using **Preload** instruction
- ❑ **Clamp** drives these values to the output pins but leaves Bypass register as the selected register

## HighZ Instruction



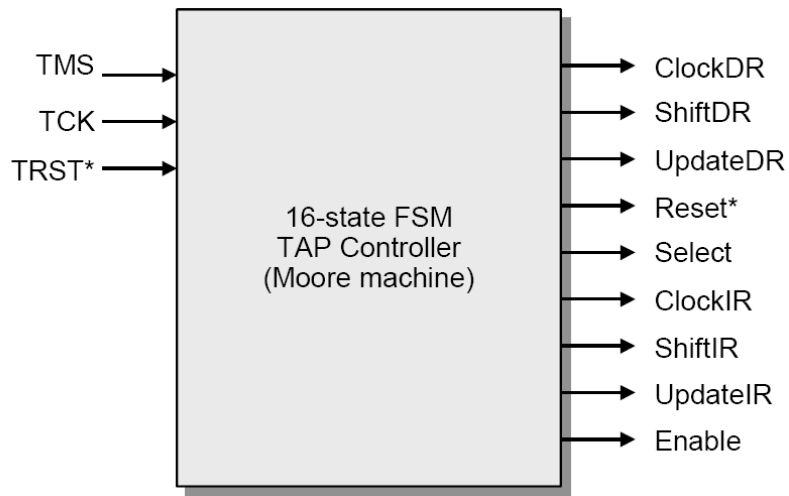
- ❑ Control-to-Z values are pre-loaded into high-Z control cells using the **Preload** instruction
- ❑ **HighZ** drives these values to the three-state controls causing them to go to their high-Z drive state but leaves Bypass register as the selected register

## Test Access Port (TAP)

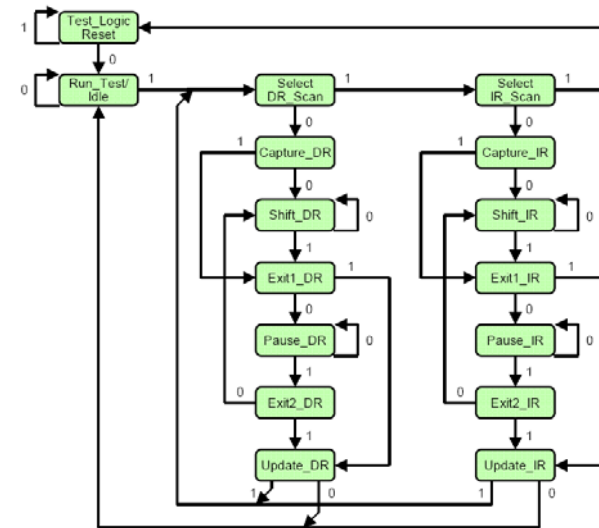


Test Data In (TDI)	Serial data in Sampled on rising edge Default = 1
Test Data Out (TDO)	Serial data out Sampled on falling edge Default = Z (only active during a shift operation)
Test Mode Select (TMS)	Input Control Sampled on rising edge Default = 1
Test Clock (TCK)	Dedicated clock Any frequency
Test Reset (TRST*)	Optional async reset Active low Default = 1

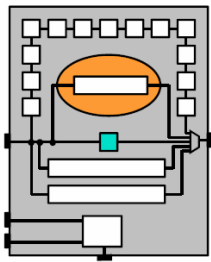
## TAP Controller



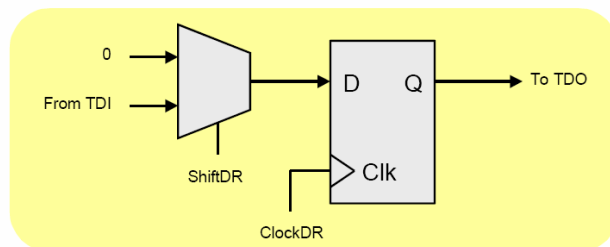
## TAP Controller State Diagram



## Bypass Register

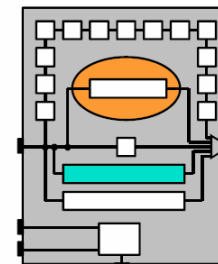


- ❑ One-bit shift register, selected by the ***Bypass*** instruction
- ❑ Captures a hard-wired 0
- ❑ Note: in the *Test-Logic/Reset* state, the Bypass register is the default register if no Identification Register present



## Identification Register

### Identification Register

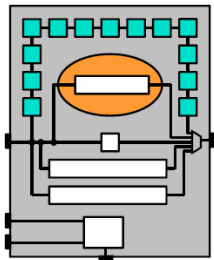


- ❑ 32-bit shift register
- ❑ Selected by ***Idcode*** and ***Usercode*** instruction
- ❑ No parallel output
- ❑ Captures a hard-wired 32-bit word
- ❑ Main function: identify device owner and part number
- ❑ Note: ***Idcode*** is power-up instruction if Identification Register is present, else ***Bypass***



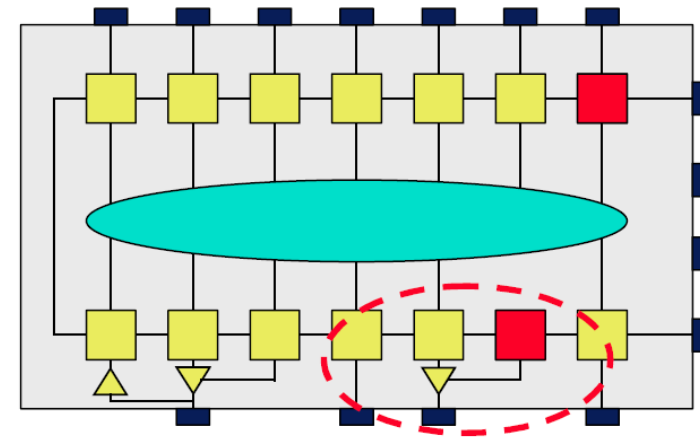


## Boundary Scan Register



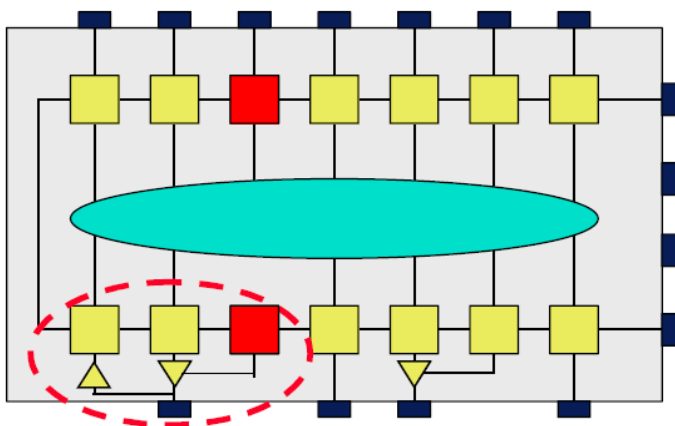
- Shift register with boundary-scan cells on:
  - device input pins
  - device output pins
  - control of three-state outputs
  - control of bidirectional cells
- Selected by the Extest, Intest, Preload and Sample instructions

## Boundary Scan Cell OZ



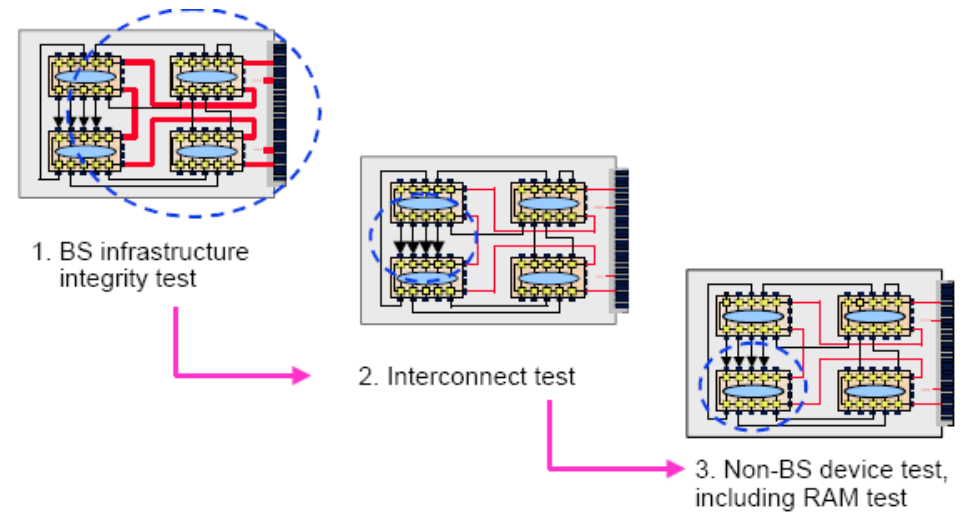
On all device signal IO, control of three-state: **dual-mode input signal** or additional scan cell

## Boundary Scan Cell IO



On control of bidirectional IO: dual-mode input signal

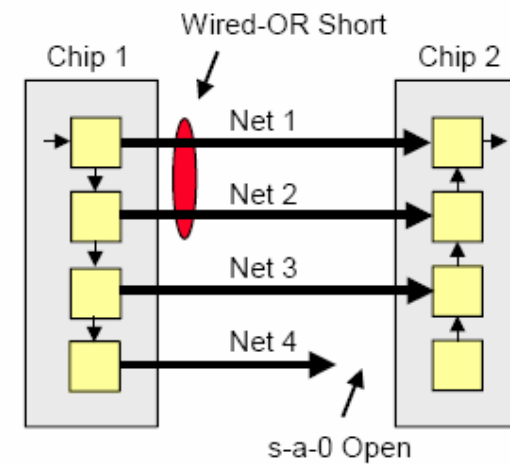
## Application at Board Level



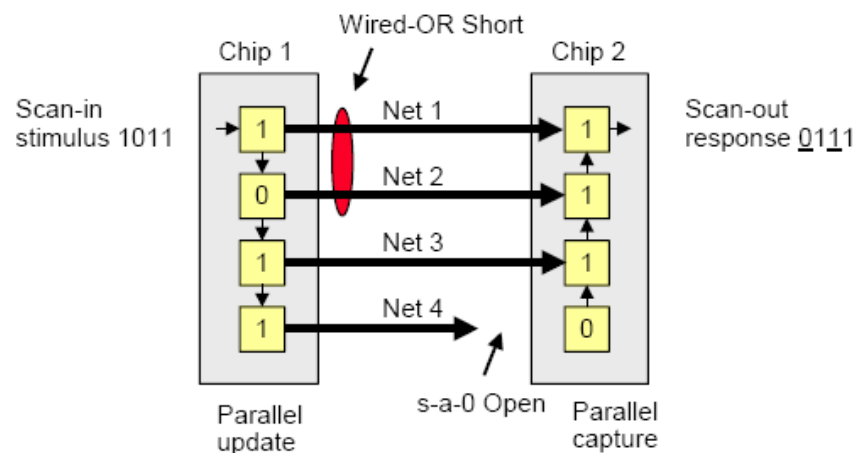
## Board Defects

- ❑ Missing component, wrong component, mis-oriented component, broken track, shorted tracks, pin-to-solder open circuit, pin-to-pin solder shorts
- ❑ Number of 2-net short circuit faults between  $k$  interconnects =  $k(k-1)/2$
- ❑ Equivalent fault models for shorts: bridging of type wired-AND and wired-OR
- ❑ Open circuits are modelled down-stream as stuck-at-1 or stuck-at-0 faults

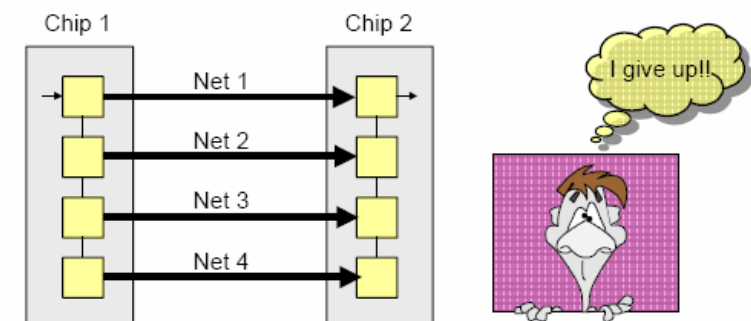
## Example of faults



## Generating Open and Short Test



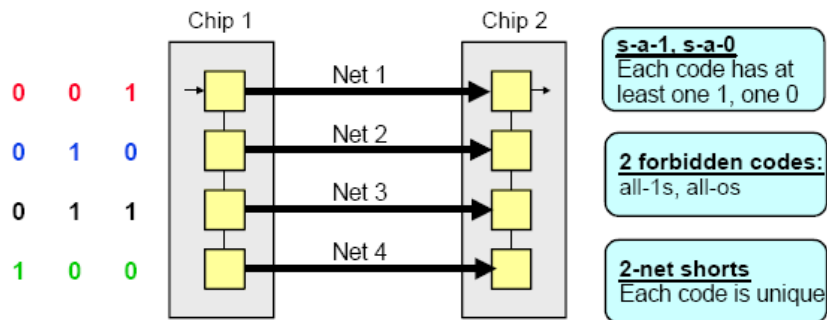
## How many tests are needed?



Determine a set of tests to detect all:

- open circuits, modelled as any net s-a-1 and s-a-0, and
- short circuits, modelled as all 2-net shorts of type wired-AND and wired-OR i.e. {1,2}, {1,3}, {1,4}, {2,3}, {2,4}, {3,4}

## Building the tests



Determine a set of tests to detect all:

- \* open circuits, modelled as any net s-a-1 and s-a-0, and
- \* short circuits, modelled as all 2-net shorts of type wired-AND and wired-OR  
i.e. {1,2}, {1,3}, {1,4}, {2,3}, {2,4}, {3,4}

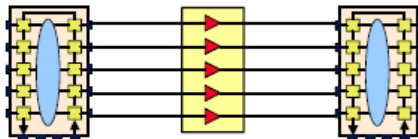
## Number of Tests

Number of tests  
 = Number of bits in the code  
 =  $\text{ceil} \log_2(k + 2)$ ,  $k$  = number of interconnects  
 = 13 for  $k = 8000$  interconnects



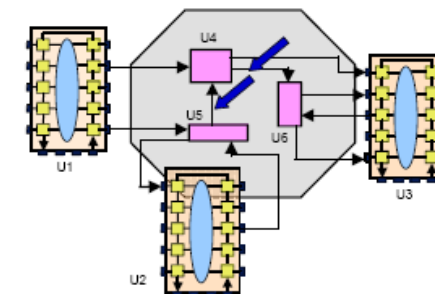
It's so simple,  
it's beautiful!!

## Testing non-Boundary Scan cluster



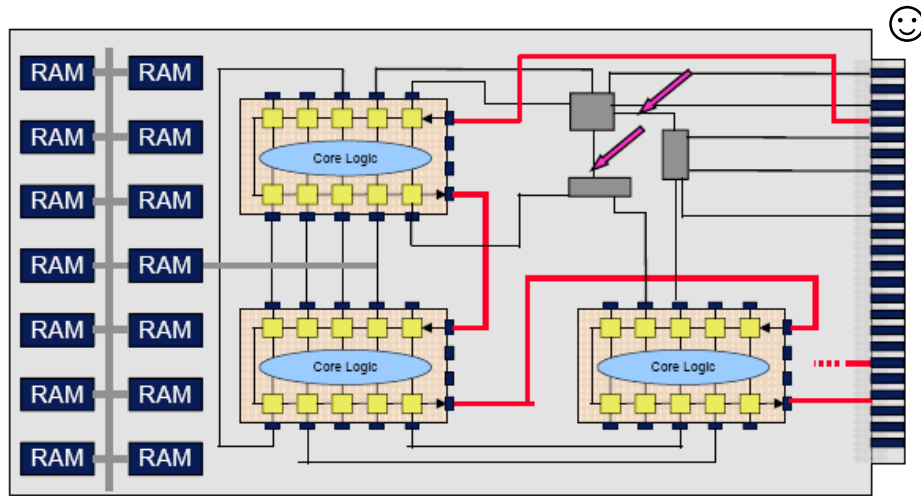
- ❑ On modern boards, most non-boundary-scan devices are simple pass-thru devices e.g. line drivers
- ❑ Consequently, tests for presence, orientation and bonding are easily generated and easily applied via the embracing boundary-scan devices

## Combining BS and Nails

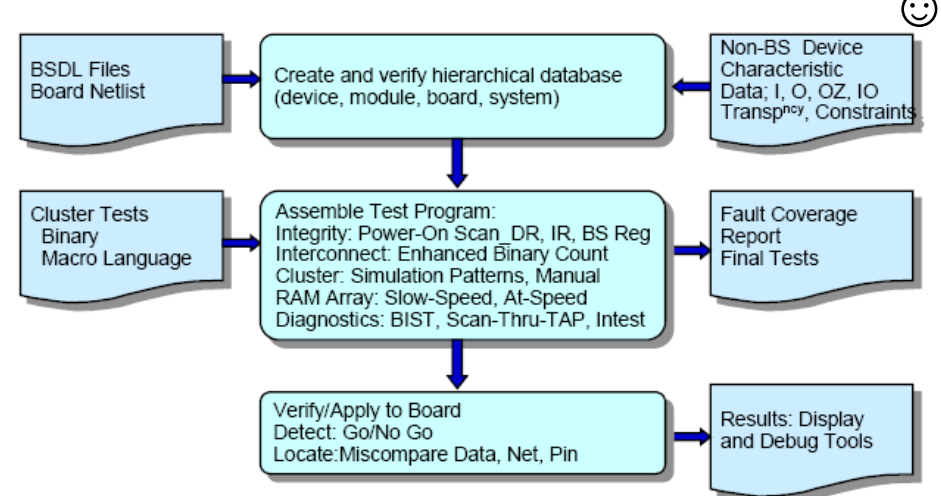


- ❑ Use ICT nails to access uncontrollable/unobservable cluster-internal nets
- ❑ Select the real-nail locations on non-BS nets according to access to:
  - strategic disables for guarding or preventing bus conflicts.
  - buried nets in non-embraced clusters
  - other key control signals e.g. O\_Enab, Bidir or 3-state control signals

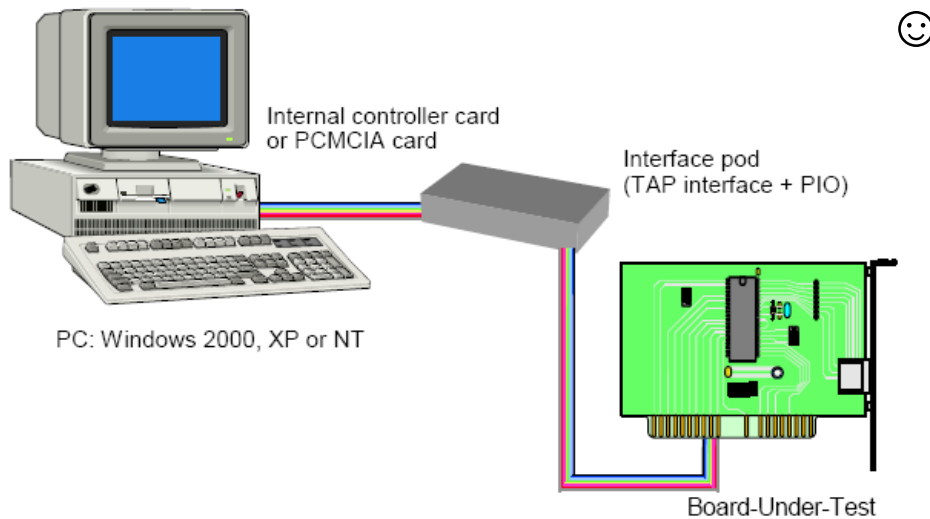
## RAM Array Testing via Boundary Scan



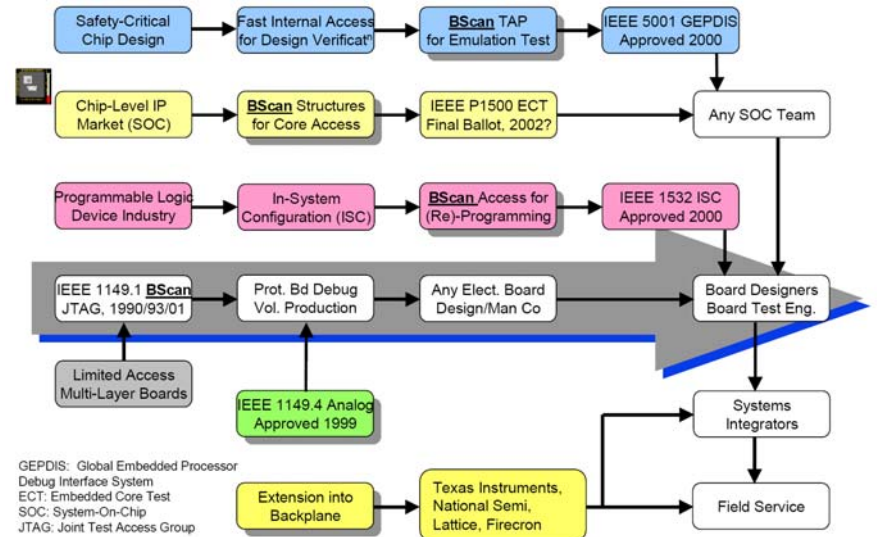
## Tool Flow for Boundary Scan Tests



## Hardware Requirement



## Where are we today?



# Spread of Design-for-Test (DFT)

Chip                      Board                      System/Field Service

